

$V_{RM} = 600\text{ V}$, $I_{F(AV)} = 60\text{ A}$, $t_{rr} = 70\text{ ns}$
Fast Recovery Diode
FMXR-4606S-SP

Description

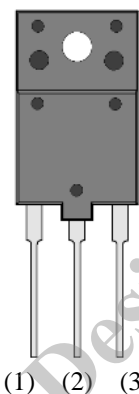
The FMXR-4606S-SP is a fast recovery diode of 600 V / 60 A. The low Q_{rr} characteristic allows the product to have almost no ringing at turn-off, leading to the realization of low-noise systems. The maximum t_{rr} of 70 ns is realized by optimizing a life-time control.

Package

TO3PF-3L

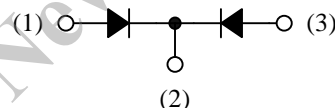
Features

- V_{RM} ----- 600 V
- $I_{F(AV)}$ ----- 60 A
- V_F ----- 2.5 V
- t_{rr} ----- 70 ns
- Q_{rr} ----- 170 nC
- Bare lead frame: Pb-free (RoHS compliant)



Applications

- CCM PFC Circuit
- Secondary Side Rectifier Diode
- Boost Diode



(1) Anode
 (2) Cathode
 (3) Anode

Not to scale

Not Recommended for New Designs

Absolute Maximum Ratings

Unless otherwise specified, $T_A = 25\text{ }^\circ\text{C}$

| Parameter | Symbol | Rating | Unit | Conditions |
|---------------------------------|-------------|------------|------------------|--|
| Peak Repetitive Reverse Voltage | V_{RSM} | 600 | V | |
| Repetitive Reverse Voltage | V_{RM} | 600 | V | |
| Average Forward Current | $I_{F(AV)}$ | 60 | A | See Figure 3 and Figure 4 |
| Surge Forward Current | I_{FSM} | 120 | A | Half cycle sine wave, positive side, 10 ms, 1 shot |
| I^2t Limiting Value | I^2t | 72 | A^2s | $1\text{ ms} \leq t \leq 10\text{ ms}$ |
| Junction Temperature | T_J | -40 to 150 | $^\circ\text{C}$ | |
| Storage Temperature | T_{STG} | -40 to 150 | $^\circ\text{C}$ | |

Electrical Characteristics

Unless otherwise specified, $T_A = 25\text{ }^\circ\text{C}$

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Unit |
|---|---------------|--|------|------|------|---------------------------|
| Forward Voltage Drop ⁽¹⁾ | V_F | $T_J = 25\text{ }^\circ\text{C}, I_F = 30\text{ A}$ | — | — | 2.5 | V |
| | | $T_J = 100\text{ }^\circ\text{C}, I_F = 30\text{ A}$ | — | 2.2 | — | V |
| Reverse Leakage Current ⁽¹⁾ | I_R | $V_R = V_{RM}$ | — | — | 10 | μA |
| Reverse Leakage Current Under High Temperature ⁽¹⁾ | $H \cdot I_R$ | $V_R = V_{RM}, T_J = 150\text{ }^\circ\text{C}$ | — | — | 1.5 | mA |
| Reverse Recovery Time ⁽¹⁾ | t_{rr} | $I_F = 30\text{ A}, V_R = 400\text{ V}, di/dt = -200\text{ A}/\mu\text{s}, 100\% \text{ recovery point}$ | — | — | 70 | ns |
| Reverse Recovery Charge ⁽¹⁾ | Q_{rr} | $I_F = 30\text{ A}, V_R = 400\text{ V}, di/dt = -200\text{ A}/\mu\text{s}, 100\% \text{ recovery point}$ | — | — | 170 | nC |
| Thermal Resistance | $R_{th(J-F)}$ | ⁽²⁾ | — | — | 0.9 | $^\circ\text{C}/\text{W}$ |
| | $R_{th(J-L)}$ | ⁽³⁾ | — | — | 1.2 | $^\circ\text{C}/\text{W}$ |

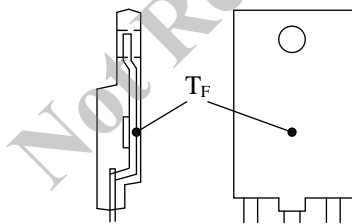


Figure 1. T_F Measurement Point

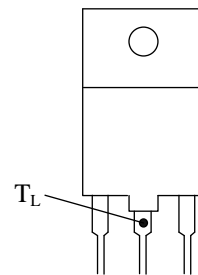


Figure 2. T_L Measurement Point

⁽¹⁾ The rating of one chip.

⁽²⁾ $R_{th(J-F)}$ is thermal resistance between junction and the flame. T_F is the flame temperature ($^\circ\text{C}$), measured at the point defined in Figure 1.

⁽³⁾ $R_{th(J-L)}$ is thermal resistance between junction and the lead. T_L is the cathode lead temperature ($^\circ\text{C}$), measured at the point defined in Figure 2.

Rating and Characteristic Curves

T_F is the flame temperature (°C), measured at the point defined in Figure 1.

T_L is the cathode lead temperature (°C), measured at the point defined in Figure 2.

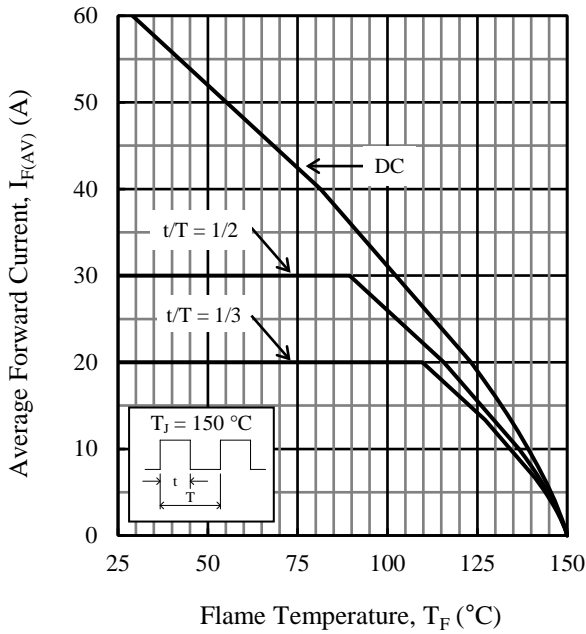


Figure 3. $I_{F(AV)}$ vs. T_F Typical Characteristics ($V_F = 0$ V)

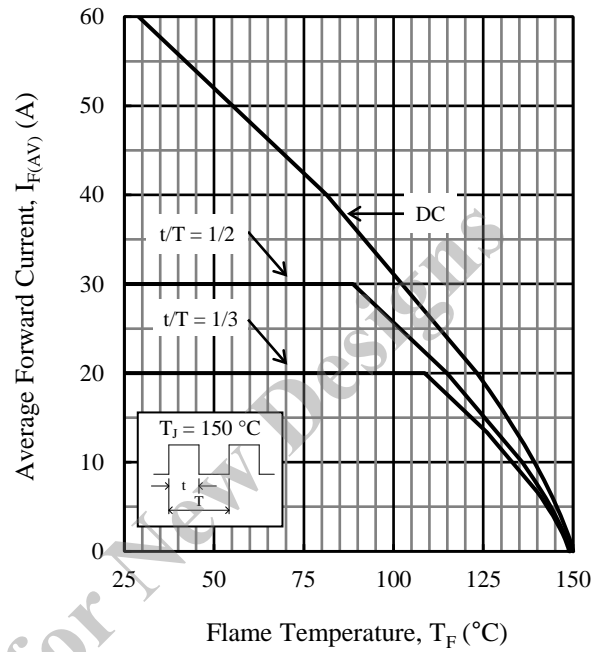


Figure 4. $I_{F(AV)}$ vs. T_F Typical Characteristics ($V_R = 600$ V)

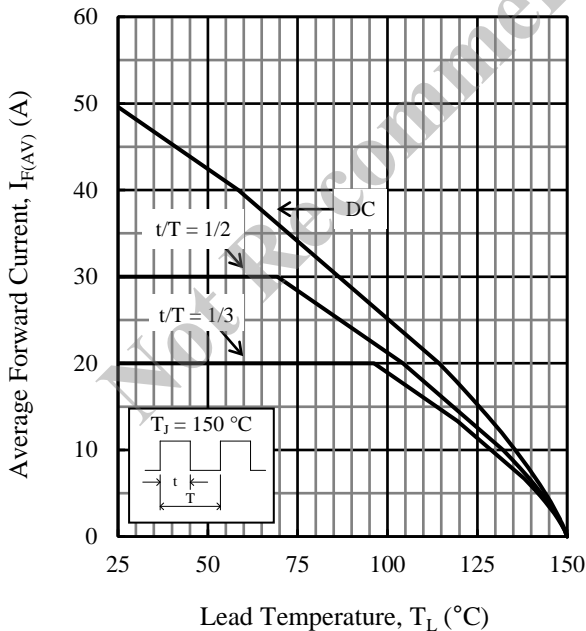


Figure 5. $I_{F(AV)}$ vs. T_L Typical Characteristics ($V_R = 0$ V)

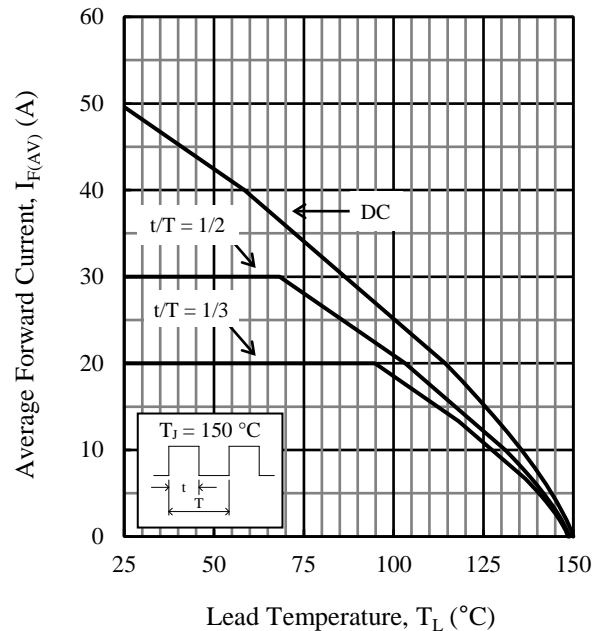


Figure 6. $I_{F(AV)}$ vs. T_L Typical Characteristics ($V_R = 600$ V)

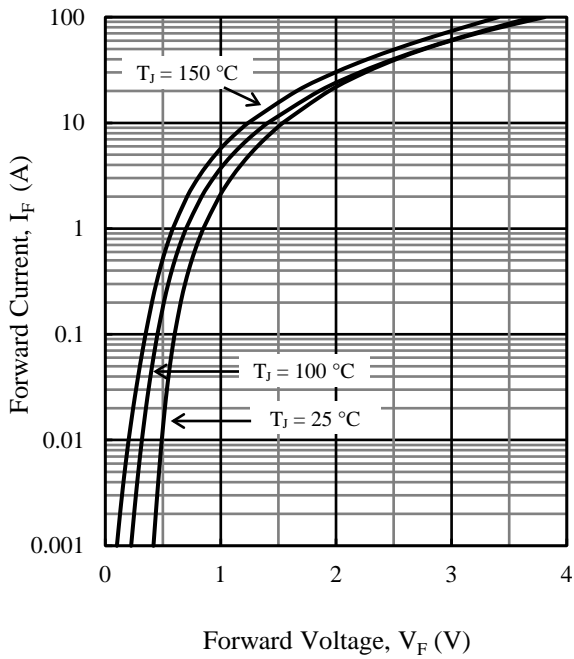


Figure 7. V_F vs. I_F Typical Characteristics

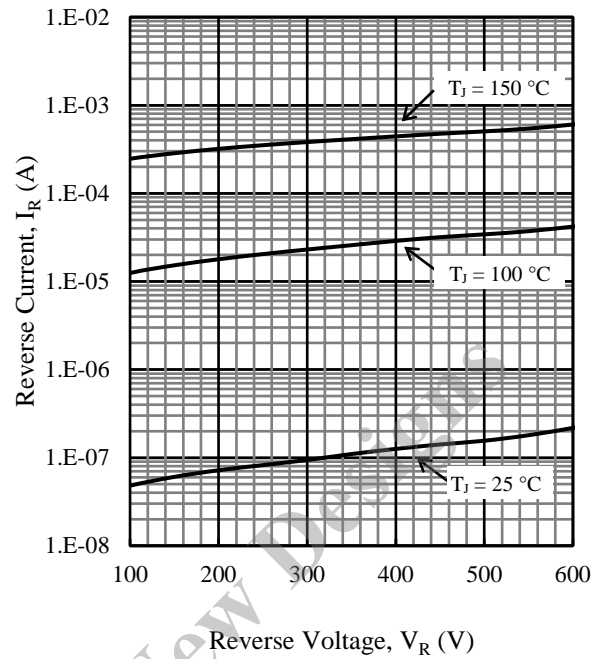


Figure 8. V_R vs. I_R Typical Characteristics

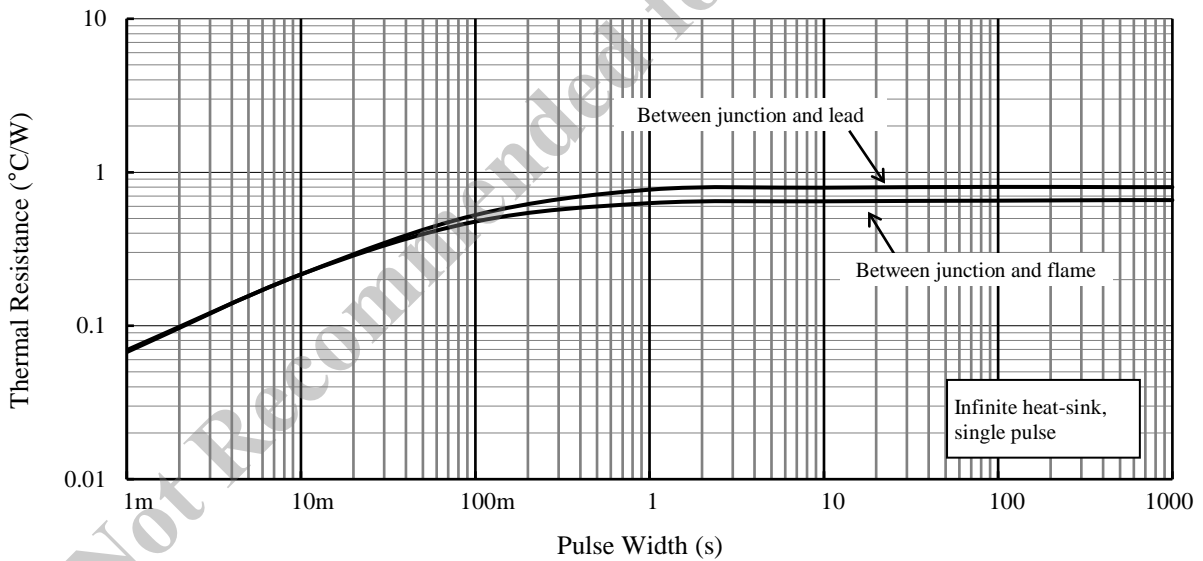
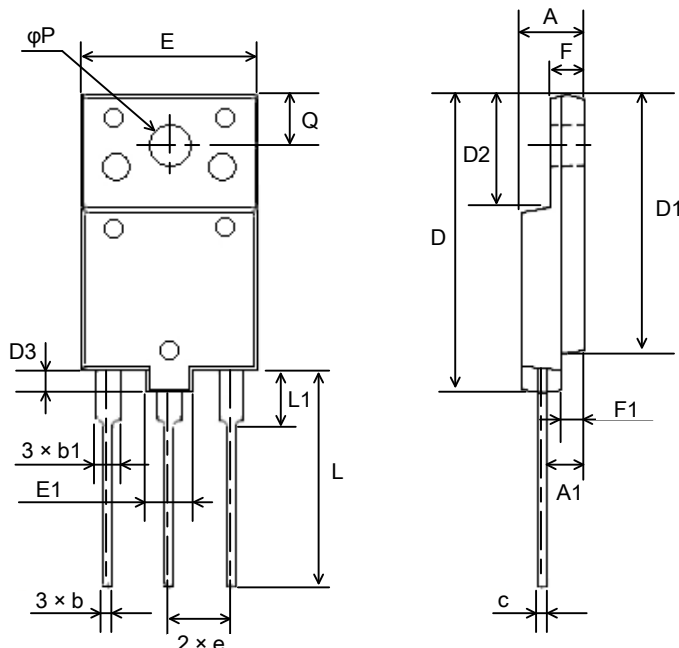


Figure 9. Typical Transient Thermal Resistance

FMXR-4606S-SP

Physical Dimensions

• TO3PF-3L

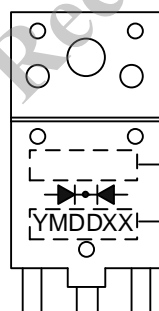


| Symbol | Min. | Nom. | Max. |
|--------|-------|-------|-------|
| A | 5.30 | 5.50 | 5.70 |
| A1 | 3.10 | 3.30 | 3.50 |
| b | 0.65 | 0.75 | 0.95 |
| b1 | 1.80 | 2.00 | 2.20 |
| c | 0.80 | 0.90 | 1.10 |
| D | 26.30 | 26.50 | 26.70 |
| D1 | 22.80 | 23.00 | 23.20 |
| D2 | 9.80 | 10.00 | 10.20 |
| D3 | 1.80 | 2.00 | 2.20 |
| E | 15.30 | 15.50 | 15.70 |
| E1 | 3.80 | 4.00 | 4.20 |
| e | 5.25 | 5.45 | 5.65 |
| F | 2.80 | 3.00 | 3.20 |
| F1 | 1.80 | 2.00 | 2.20 |
| L | 19.10 | 19.30 | 19.50 |
| L1 | 4.80 | 5.00 | 5.20 |
| Q | 4.30 | 4.50 | 4.70 |
| φP | 3.40 | 3.60 | 3.80 |

NOTES:

- Dimensions in millimeters
- Bare lead frame: Pb-free (RoHS compliant)
- When soldering the products, it is required to minimize the working time, within the following limits:
 Flow: $260 \pm 5 \text{ }^\circ\text{C} / 10 \pm 1 \text{ s}$, 2 times
 Soldering Iron: $380 \pm 10 \text{ }^\circ\text{C} / 3.5 \pm 0.5 \text{ s}$, 1 time
 Soldering should be at a distance of at least 1.5 mm from the body of the product.
- Recommended screw torque for TO3PF: 0.686 N·m to 0.882 N·m (7 kgf·cm to 9 kgf·cm)

Marking Diagram



Specific Device Code (See Table 1)

Lot Number:

Y is the last digit of the year of manufacture (0 to 9)

M is the month of the year (1 to 9, O, N, or D)

DD is the day of the month (01 to 31)

XX is the control number

Table 1. Specific Device Code

| Specific Device Code | Part Number |
|----------------------|---------------|
| XR4606 | FMXR-4606S-SP |

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